

Customer Notification of Product/Process Changes

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*Subject:Planarwafer IR improvement

*Issued Date: July/26/2019

*Effective date:Nov/01/2019

*Affected category:SMD B3200B product

*Affected Family: see attached file

Change Item	MaterialDesignProcess _ Others
Impact Item	1. ProductP/N : ☐ Yes ■ No3. Label : ☐ Yes ■ No
•	
	2. Marking : ☐Yes ■ No4. Other items : ☐ Yes ■ No
Other Related	NA .
item	
Change	IR improvement
Purpose	
Description of Change	Wafer passivation optimization
	■Electrical Test Report (as the attachment) SGS / MCD_MDS Report
Related	□ESD Report (as the attachment)□MechanicalTest Report
Report	
	Others(ex. Impacted part list) (as the attachment)
Sample availability	■Yes □No
Customor	☐ Approve
Customer Approval	□ Disapprove
C	
Customer	
Requirement	·
(ex. Last Buy requirement)	
1	

(Note):

- 1.If you need sample(s) or any question, please contact with our Salesperson within 30day
- 2.LSC will follow WW industry standard spec (JESD46D) criteria define as below.
- A. Customers should acknowledge receipt of the PCN within 30 day period constitutes
- B. Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.
- C. After acknowledgement, lack of additional response within the 90 day period constitutes acceptance of the change.
- D. If customer requires additional time to perform samples testing, beyond the 90 day review period an extension must be negotiate

Quality Assurance

LITEON LITE-ON SEMICONDUCTOR

Attachments:

- Part list of wafer passivation optimization
 Wafer passiviation optimization structure

- 3. IR (Reliability) distribution comparison4. IR (Normal testing)distribution comparison
- 5. Reliability test summary